

SOT1119-1

plastic thermal enhanced ball grid array package; 432 balls;
heatsink

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | B (bottom) |
| Package type descriptive code | HBGA432 |
| Package type industry code | HBGA432 |
| Package style descriptive code | HBGA (thermal enhanced ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | 144E |
| JEDEC package outline code | MS-034 |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 14-8-2009 |

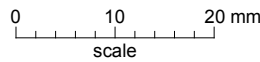
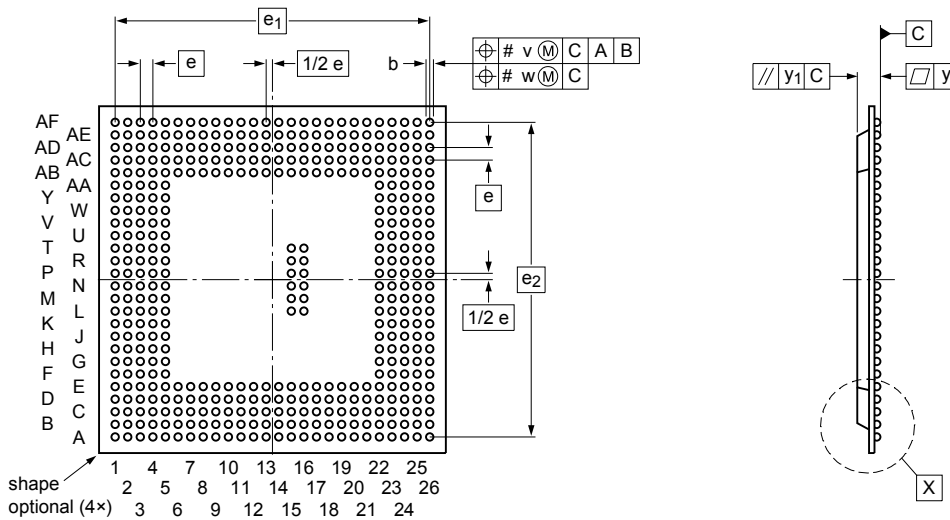
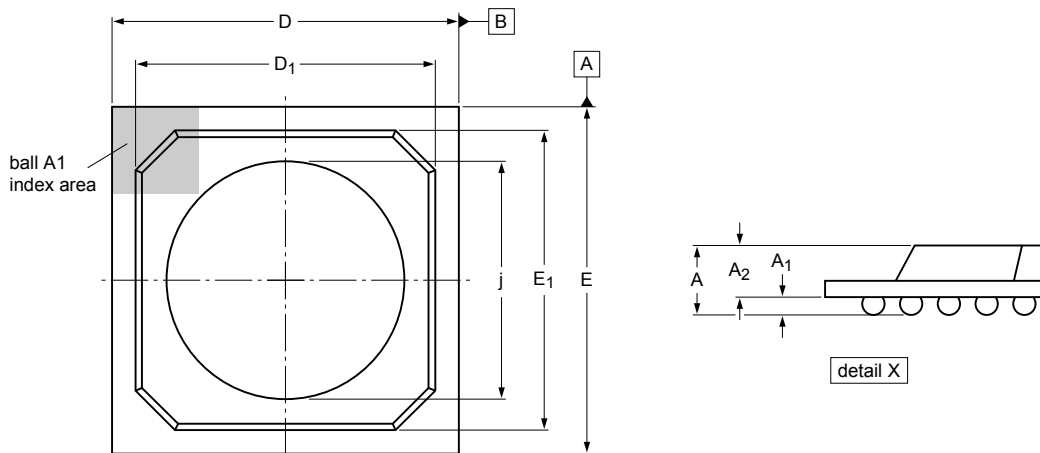
Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|------|-----|------|------|------|
| D | package length | 34.8 | - | 35 | 35.2 | mm |
| E | package width | 34.8 | - | 35 | 35.2 | mm |
| A | seated height | 2.15 | - | 2.35 | 2.55 | mm |
| A ₂ | package height | 1.6 | - | 1.75 | 1.85 | mm |
| e | nominal pitch | - | - | 1.27 | - | mm |
| n ₂ | actual quantity of termination | - | - | 432 | - | |



2. Package outline

HBGA432: plastic thermal enhanced ball grid array package; 432 balls; heatsink SOT1119-1



Dimensions

| Unit | A | A ₁ | A ₂ | b | D | D ₁ | E | E ₁ | e | e ₁ | e ₂ | j | v | w | y | y ₁ |
|--------|------|----------------|----------------|------|------|----------------|------|----------------|------|----------------|----------------|----|-----|------|------|----------------|
| max | 2.55 | 0.7 | 1.85 | 0.90 | 35.2 | 30.75 | 35.2 | 30.75 | | | | 26 | | | | |
| mm nom | 2.35 | 0.6 | 1.75 | 0.75 | 35.0 | 30.25 | 35.0 | 30.25 | 1.27 | 31.75 | 31.75 | 24 | 0.3 | 0.15 | 0.15 | 0.35 |
| min | 2.15 | 0.5 | 1.60 | 0.60 | 34.8 | 29.75 | 34.8 | 29.75 | | | | 22 | | | | |

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| Outline version | References | | | European projection | Issue date |
|-----------------|------------|--------|-------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT1119-1 | 144E | MS-034 | --- | | 08-10-15 09-08-14 |

Fig. 1. Package outline HBGA432 (SOT1119-1)

3. Legal information

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4. Contents

| | |
|---------------------------|---|
| 1. Package summary..... | 1 |
| 2. Package outline..... | 2 |
| 3. Legal information..... | 3 |

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